the capacitor comprises a plurality of capacitor terminals, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

the IC chip comprises a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals;

the plurality of capacitor terminals of the capacitor are respectively flip-chip-bonded directly to a plurality of connection-to-capacitor terminals of the IC chip; and

the plurality of substrate terminals of the printed wiring substrate are respectively flip-chip-bonded to a plurality of connection-to-substrate terminals of the IC chip.

2. (Thrice amended) A printed wiring substrate having a planar surface and a built-in capacitor on which an IC-chip-carrying printed wiring substrate is mounted, said printed wiring substrate comprising a capacitor accommodation cavity for accommodating the capacitor, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

the capacitor comprises a plurality of capacitor terminals, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

the IC chip-carrying printed wiring circuit comprises a plurality of connection-to capacitor terminals and a plurality of connection-to-substrate terminals;

the plurality of capacitor terminals of the capacitor are respectively bonded in a connection-face-to-connection-face manner directly to a plurality of connection-to-capacitor terminals of the IC-chip-carrying printed wiring substrate; and

the plurality of substrate terminals of the printed wiring substrate are respectively bonded in a connection-face-to-connection-face manner to a plurality of connection-to-substrate terminals of the IC-chip-carrying printed wiring substrate.

4. (Thrice amended) A printed wiring substrate having a planar surface and a built-in capacitor for mounting an IC chip or IC-chip-carrying printed wiring substrate having a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals, said printed wiring substrate comprising a capacitor accommodation cavity for accommodating the capacitor, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

the capacitor comprises a plurality of capacitor terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to a plurality of connection-to-capacitor terminals of the IC chip or IC-chip-carrying printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode group; and

the printed wiring substrate comprises a plurality of substrate terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner directly to a plurality of connection-to-substrate terminals of the IC chip or IC-chip-carrying printed wiring substrate.